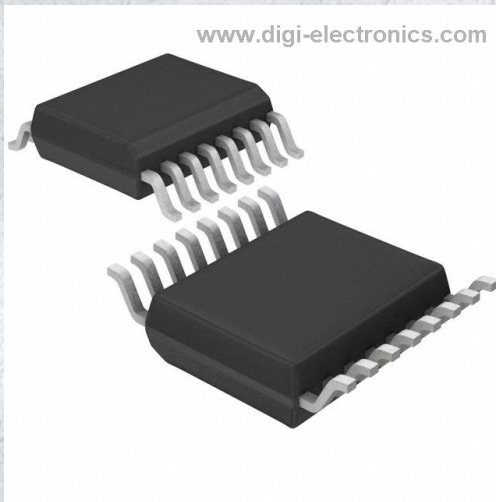


MC100LVEP34DT Datasheet



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	MC100LVEP34DT-DG
Manufacturer	onsemi
Manufacturer Product Number	MC100LVEP34DT
Description	IC CLOCK GENERATOR 16TSSOP
Detailed Description	Clock Generator IC 2.8GHz 1 16-TSSOP (0.173", 4.40 mm Width)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

MC100LVEP34DT

Series:

100LVEP

DiGi-Electronics Programmable:

Not Verified

PLL:

No

Output:

ECL

Ratio - Input:Output:

1:3

Frequency - Max:

2.8GHz

Voltage - Supply:

2.375V ~ 3.8V

Mounting Type:

Surface Mount

Supplier Device Package:

16-TSSOP

Manufacturer:

onsemi

Product Status:

Obsolete

Type:

Clock Generator

Input:

CML, LVDS, NECL, PECL

Number of Circuits:

1

Differential - Input:Output:

Yes/Yes

Divider/Multiplier:

Yes/No

Operating Temperature:

-40°C ~ 85°C

Package / Case:

16-TSSOP (0.173", 4.40mm Width)

Base Product Number:

MC100LV

Environmental & Export classification

RoHS Status:

RoHS non-compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

2.5 V/3.3 V ECL ÷2, ÷4, ÷8 Clock Generation Chip

MC100LVEP34

Description

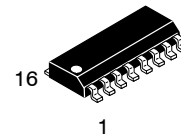
The MC100LVEP34 is a low skew ÷2, ÷4, ÷8 clock generation chip designed explicitly for low skew clock generation applications. The internal dividers are synchronous to each other, therefore, the common output edges are all precisely aligned. The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The common enable ($\overline{\text{EN}}$) is synchronous so that the internal dividers will only be enabled/disabled when the internal clock is already in the LOW state. This avoids any chance of generating a runt clock pulse on the internal clock when the device is enabled/disabled as can happen with an asynchronous control. An internal runt pulse could lead to losing synchronization between the internal divider stages. The internal enable flip-flop is clocked on the falling edge of the input clock; therefore, all associated specification limits are referenced to the negative edge of the clock input.

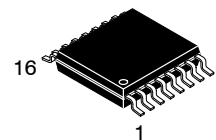
Upon start-up, the internal flip-flops will attain a random state; the master reset (MR) input allows for the synchronization of the internal dividers, as well as multiple LVEP34s in a system. Single-ended CLK input operation is limited to a $V_{CC} \geq 3.0 \text{ V}$ in PECL mode, or $V_{EE} \leq -3.0 \text{ V}$ in NECL mode.

Features

- 35 ps Output-to-Output Skew
- Synchronous Enable/Disable
- Master Reset for Synchronization
- The 100 Series Contains Temperature Compensation.
- PECL Mode Operating Range: $V_{CC} = 2.375 \text{ V}$ to 3.8 V with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0 \text{ V}$ with $V_{EE} = -2.375 \text{ V}$ to -3.8 V
- Open Input Default State
- LVDS Input Compatible
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

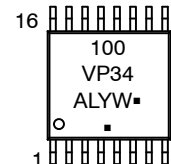
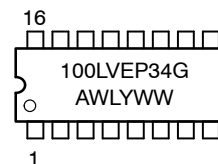


SO-16
D SUFFIX
CASE 751B



TSSOP-16
DT SUFFIX
CASE 948F

MARKING DIAGRAMS*



- A = Assembly Location
L, WL = Wafer Lot
Y = Year
W, WW = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

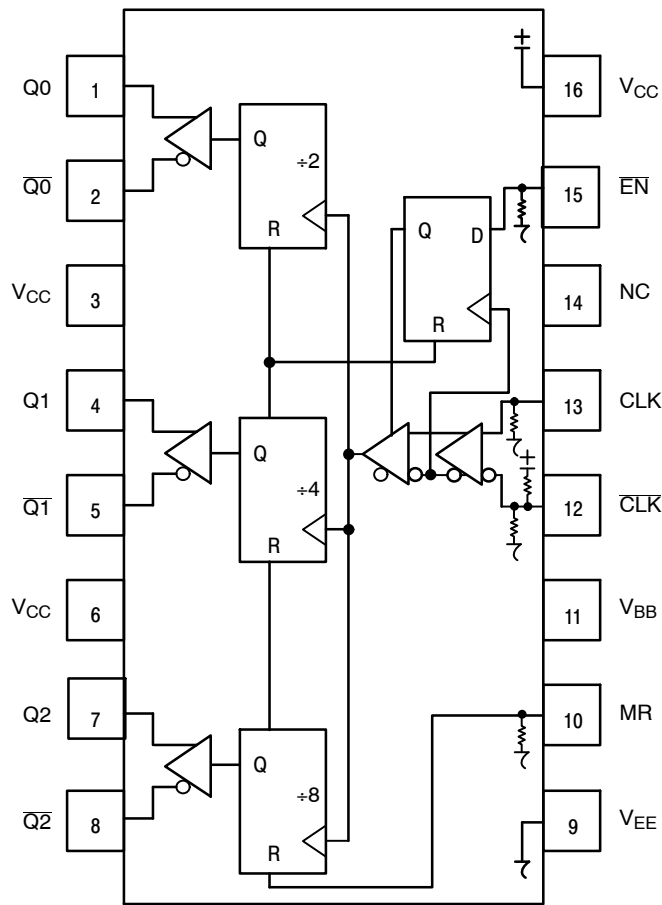
*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100LVEP34DG	SOIC-16 (Pb-Free)	48 Units / Tube
MC100LVEP34DTG	TSSOP-16 (Pb-Free)	96 Units / Tube
MC100LVEP34DTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

MC100LVEP34



Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 16-Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Function
CLK*, CLK**	ECL Diff Clock Inputs
EN*	ECL Sync Enable
MR*	ECL Master Reset
Q0, Q0̄	ECL Diff +2 Outputs
Q1, Q1̄	ECL Diff +4 Outputs
Q2, Q2̄	ECL Diff +8 Outputs
V _{BB}	Reference Voltage Output
V _{CC}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect

* Pins will default LOW when left open.

**Pins will default to V_{CC}/2 when left open.

Table 2. FUNCTION TABLE

CLK	EN	MR	FUNCTION
Z	L	L	Divide
ZZ	H	L	Hold Q ₀₋₃
X	X	H	Reset Q ₀₋₃

Z = Low-to-High Transition

ZZ = High-to-Low Transition

MC100LVEP34**Table 3. ATTRIBUTES**

Characteristics	Value
Internal Input Pulldown Resistor	75 k Ω
Internal Input Pullup Resistor	37.5 k Ω
ESD Protection Human Body Model Machine Model Charged Device Model	> 2 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-O @ 0.125 in
Transistor Count	210 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note [AND8003/D](#).

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
V _I	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	V _I \leq V _{CC} V _I \geq V _{EE}	6 -6	V V
I _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BB} Sink/Source			\pm 0.5	mA
T _A	Operating Temperature Range			-40 to +85	$^{\circ}$ C
T _{stg}	Storage Temperature Range			-65 to +150	$^{\circ}$ C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-16 SOIC-16	100 60	$^{\circ}$ C/W $^{\circ}$ C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-16	33 to 36	$^{\circ}$ C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-16 TSSOP-16	138 108	$^{\circ}$ C/W $^{\circ}$ C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-16	33 to 36	$^{\circ}$ C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248 $^{\circ}$ C		265	$^{\circ}$ C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MC100LVEP34**Table 5. 100EP DC CHARACTERISTICS, PECL** $V_{CC} = 2.5\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 2)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	40	50	60	40	50	60	42	52	62	mA
V_{OH}	Output HIGH Voltage (Note 3)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V_{OL}	Output LOW Voltage (Note 3)	505	680	900	505	680	900	505	680	900	mV
V_{IH}	Input HIGH Voltage (Single-Ended) (Note 4)	1335		1620	1335		1620	1275		1620	mV
V_{IL}	Input LOW Voltage (Single-Ended) (Note 4)	505		900	505		900	505		900	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 4, Note 5)	1.2		3.3	1.2		3.3	1.2		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

- Input and output parameters vary 1:1 with V_{CC} .
- All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.
- Do not use V_{BB} at $V_{CC} < 3.0\text{ V}$. Single-Ended input CLK pin operation is limited to $V_{CC} \geq 3.0\text{ V}$ in PECL mode.
- V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 6. 100EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 6)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	40	50	60	40	50	60	42	52	62	mA
V_{OH}	Output HIGH Voltage (Note 7)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V_{OL}	Output LOW Voltage (Note 7)	1305	1570	1700	1305	1570	1700	1305	1570	1700	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
V_{IL}	Input LOW Voltage (Single-Ended)	1305		1700	1305		1700	1305		1700	mV
V_{BB}	Output Voltage Reference (Note 8)	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 9)	1.2		3.3	1.2		3.3	1.2		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

- Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $+0.925\text{ V}$ to -0.5 V .
- All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.
- Single-Ended input CLK pin operation is limited to $V_{CC} \geq 3.0\text{ V}$ in PECL mode.
- V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

MC100LVEP34

Table 7. 100EP DC CHARACTERISTICS, NECL $V_{CC} = 0\text{ V}$, $V_{EE} = -3.8\text{ V}$ to -2.375 V (Note 10)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	40	50	60	40	50	60	42	52	62	mA
V_{OH}	Output HIGH Voltage (Note 11)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V_{OL}	Output LOW Voltage (Note 11)	-1995	-1700	-1600	-1995	-1700	-1600	-1995	-1700	-1600	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1995		-1600	-1995		-1600	-1995		-1600	mV
V_{BB}	Output Voltage Reference (Note 12)	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 13)	$V_{EE}+1.2$		0.0	$V_{EE}+1.2$		0.0	$V_{EE}+1.2$		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current D \bar{D}	0.5 -150			0.5 -150			0.5 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

10. Input and output parameters vary 1:1 with V_{CC} .

11. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

12. Single-Ended input CLK pin operation is limited to $V_{EE} \leq -3.0\text{ V}$ in NECL mode.

13. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 8. AC CHARACTERISTICS $V_{CC} = 0\text{ V}$; $V_{EE} = -3.8\text{ V}$ to -2.375 V or $V_{CC} = 2.375\text{ V}$ to 3.8 V ; $V_{EE} = 0\text{ V}$ (Note 14)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency (See Figure 4. F_{max})	2.8			2.8			2.8			GHz
t_{PLH} t_{PHL}	Propagation Delay to Output CLK to Q0, Q1, Q2 MR to Q	550 500	650 600	750 700	600 550	700 650	800 750	650 600	750 700	850 800	ps
t_{JITTER}	RMS Clock Jitter (See Figure 4. $F_{max}/JITTER$) DIV2 $\leq 2.5\text{ GHz}$ DIV2 $\leq 3.0\text{ GHz}$ DIV4 $\leq 2.5\text{ GHz}$ DIV4 $\leq 3.0\text{ GHz}$ DIV8 $\leq 2.5\text{ GHz}$ DIV8 $\leq 3.0\text{ GHz}$		0.36 0.34 0.26 0.32 0.27 0.32	0.4 0.4 0.4		0.30 0.40 0.29 0.38 0.30 0.39	0.4 0.5 0.5		0.35 0.63 0.33 0.60 0.34 1.10	0.6 0.5 0.5	ps
t_S	Setup Time $\bar{E}N$	150	50		150	50		150	50		ps
t_H	Hold Time $\bar{E}N$	200	100		200	100		200	100		ps
t_{RR}	Set/Reset Recovery	300	200		300	200		300	200		ps
V_{PP}	Input Swing (Note 15)	150		1000	150		1000	150		1000	mV
t_r t_f	Output Rise/Fall Times Q (20% - 80%)	90	170	200	100	180	250	120	200	280	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

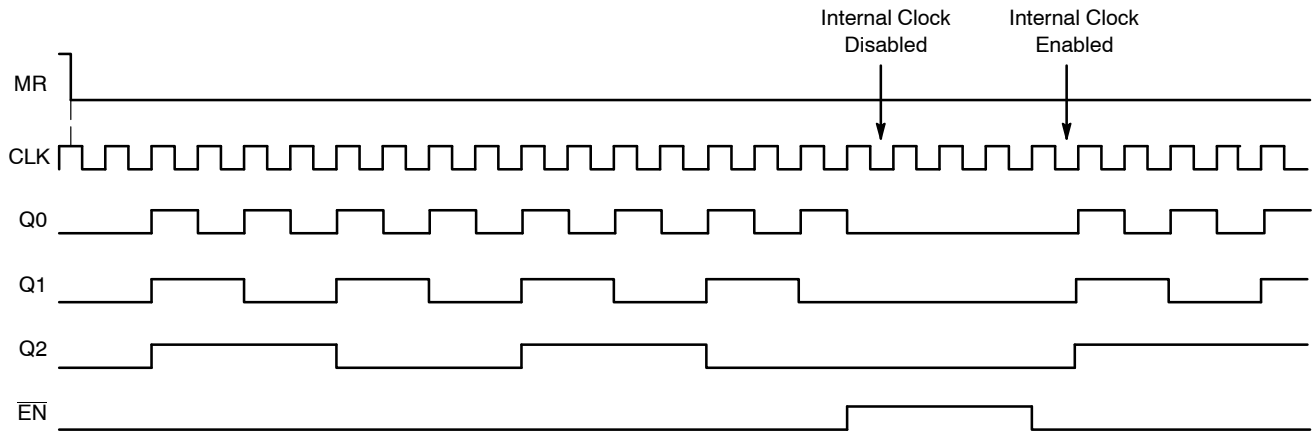
14. Measured using a 750 mV source, 50% duty cycle clock source. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

15. $V_{PP(min)}$ is minimum input swing for which AC parameters guaranteed. The device has a DC gain of ≈ 40 .

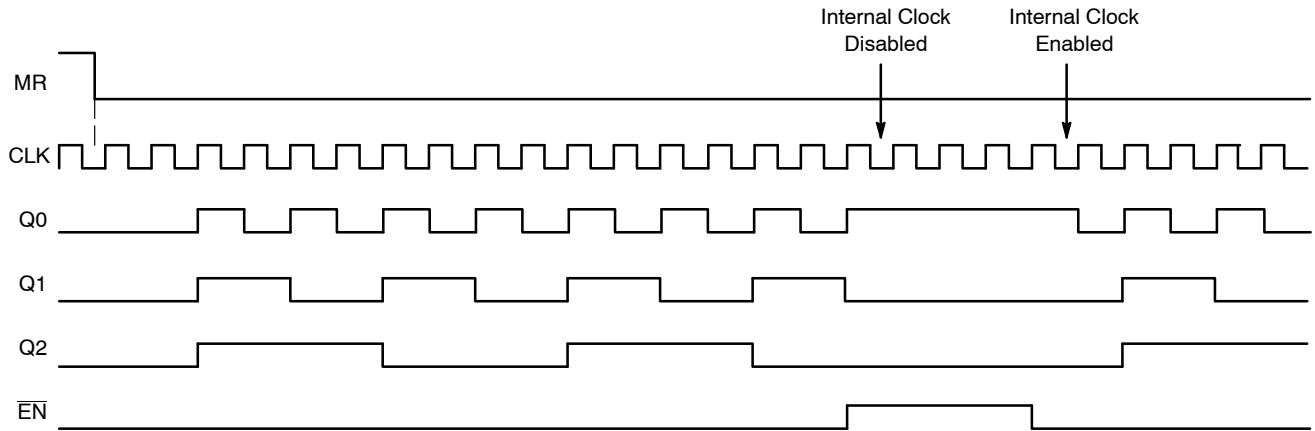
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MC100LVEP34

There are two distinct functional relationships between the Master Reset and Clock:



CASE 1: If the MR is de-asserted (H-L), while the Clock is still high, the outputs will follow the second ensuing clock rising edge.



CASE 2: If the MR is de-asserted (H-L), after the Clock has transitioned low, the outputs will follow the third ensuing clock rising edge.

Figure 2. Timing Diagrams

The \overline{EN} signal will “freeze” the internal divider flip-flops on the first falling edge of CLK after its assertion. The internal divider flip-flops will maintain their state during the freeze. When \overline{EN} is deasserted (LOW), and after the next falling edge of CLK, then the internal divider flip-flops will “unfreeze” and continue to their next state count with proper phase relationships.

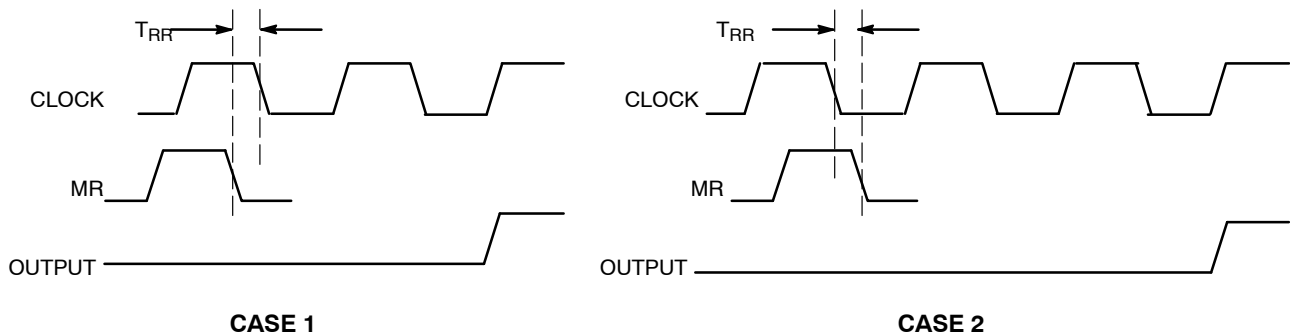


Figure 3. Reset Recovery Time

MC100LVEP34

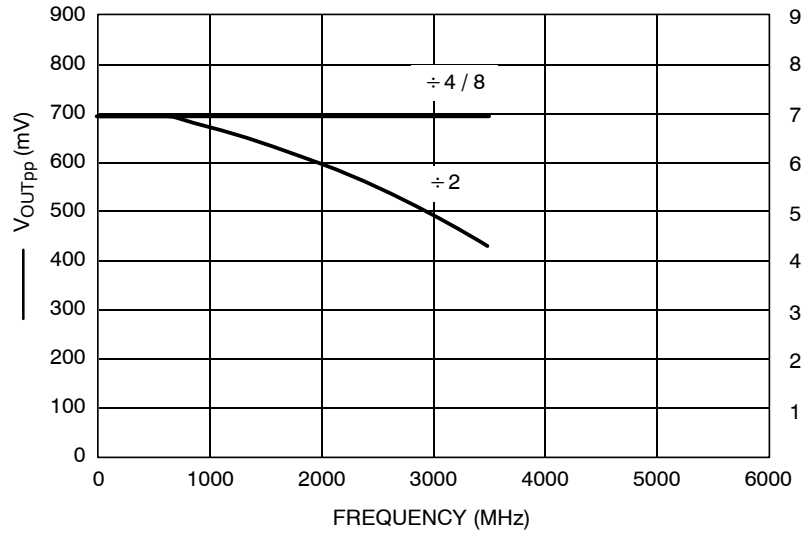


Figure 4. F_{max}

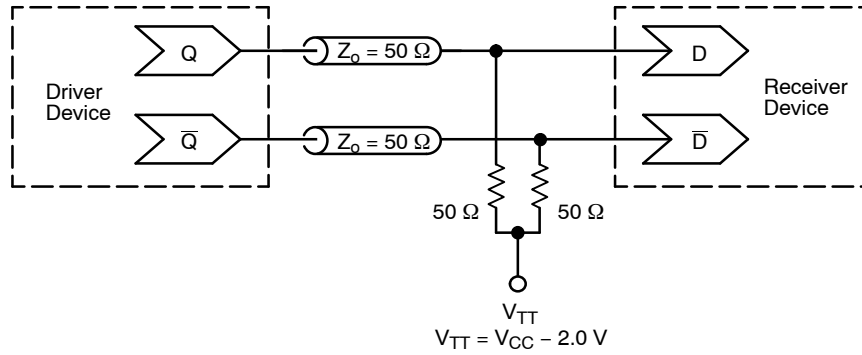


Figure 5. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices.)

MC100LVEP34

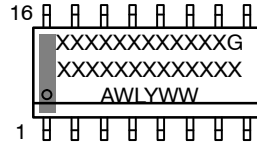
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

SOIC-16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M

DATE 18 OCT 2024

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 Y = Year
 WW = Work Week
 G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

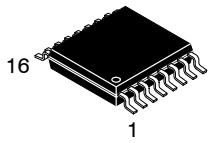
<p>STYLE 1:</p> <p>PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR</p>	<p>STYLE 2:</p> <p>PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE</p>	<p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4</p>	<p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1</p>
<p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1</p>	<p>STYLE 6:</p> <p>PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE</p>	<p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH</p>	

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DESCRIPTION:	SOIC-16 9.90X3.90X1.37 1.27P	PAGE 2 OF 2

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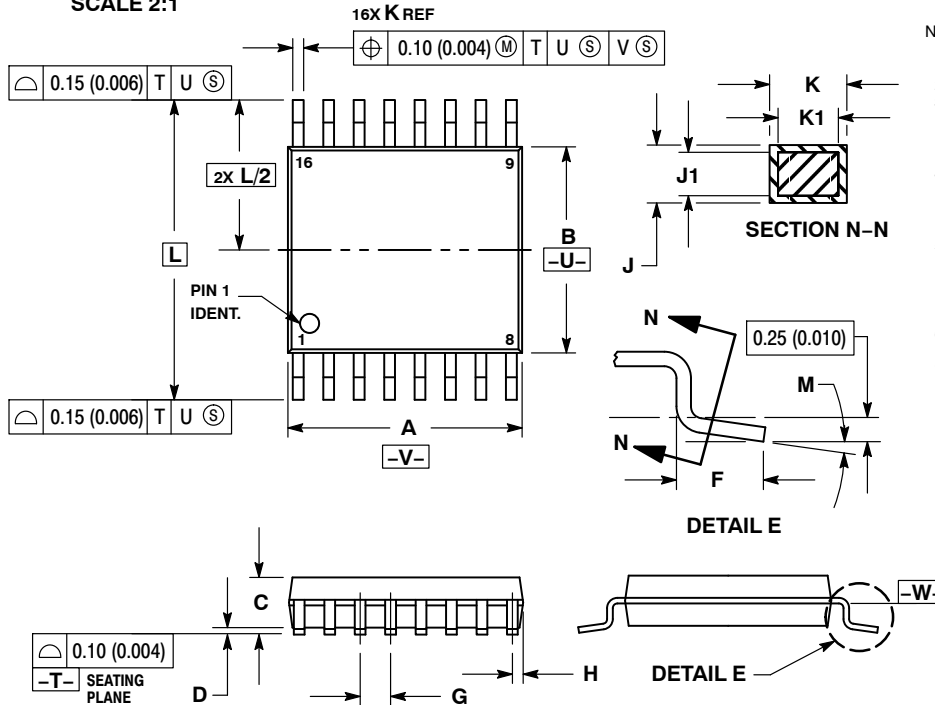


**MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS**



**TSSOP-16 WB
CASE 948F
ISSUE B**

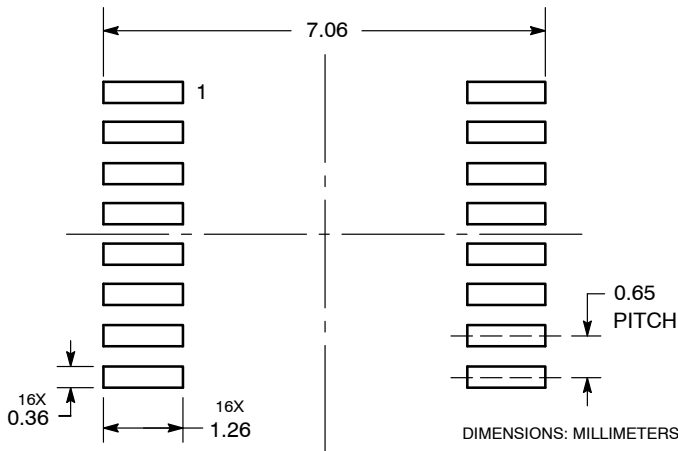
DATE 19 OCT 2006



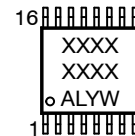
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**RECOMMENDED
SOLDERING FOOTPRINT***



**GENERIC
MARKING DIAGRAM***



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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